

# CP398X-CPDM303NH-WN Datasheet



DiGi Electronics Part Number	CP398X-CPDM303NH-WN-DG
Manufacturer	<a href="#">Central Semiconductor Corp</a>
Manufacturer Product Number	CP398X-CPDM303NH-WN
Description	MOSFET N-CH 30V 3.6A DIE
Detailed Description	N-Channel 30 V 3.6A (Ta) Surface Mount Die

<https://www.DiGi-Electronics.com>

This model CP398X-CPDM303NH-WN is available at DiGi Electronics.

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We welcome your inquiries regarding pricing, lead time, or other product-related questions.

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RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

DiGi is a global authorized distributor of electronic components.

## Purchase and inquiry

Manufacturer Product Number:

CP398X-CPDM303NH-WN

Series:

-

FET Type:

N-Channel

Drain to Source Voltage (Vdss):

30 V

Drive Voltage (Max Rds On, Min Rds On):

2.5V, 4.5V

Vgs(th) (Max) @ Id:

1.2V @ 250 $\mu$ A

Vgs (Max):

12V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

Die

Base Product Number:

CP398

Manufacturer:

Central Semiconductor Corp

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

3.6A (Ta)

Rds On (Max) @ Id, Vgs:

78mOhm @ 1.8A, 2.5V

Gate Charge (Qg) (Max) @ Vgs:

13 nC @ 4.5 V

Input Capacitance (Ciss) (Max) @ Vds:

590 pF @ 10 V

Power Dissipation (Max):

-

Mounting Type:

Surface Mount

Package / Case:

Die

## Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

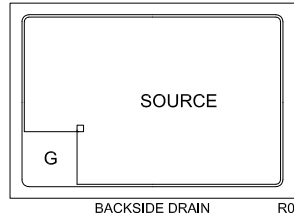
EAR99

# CP398X-CPDM303NH

## N-Channel MOSFET Die

### Enhancement-Mode

The CP398X-CPDM303NH is a silicon N-Channel MOSFET designed for high speed pulsed amplifier and driver applications.



#### MECHANICAL SPECIFICATIONS:

Die Size	37.8 x 26 MILS
Die Thickness	5.5 MILS
Gate Bonding Pad Size	7.3 x 7.3 MILS
Source Bonding Pad Size	34 x 22.2 MILS
Top Side Metalization	Al – 40,000Å
Back Side Metalization	Ti/Ni/Ag – 1,000Å/3,000Å/10,000Å
Scribe Alley Width	2.36 MILS
Wafer Diameter	8 INCHES
Gross Die Per Wafer	45,000

#### MAXIMUM RATINGS: ( $T_A=25^\circ\text{C}$ )

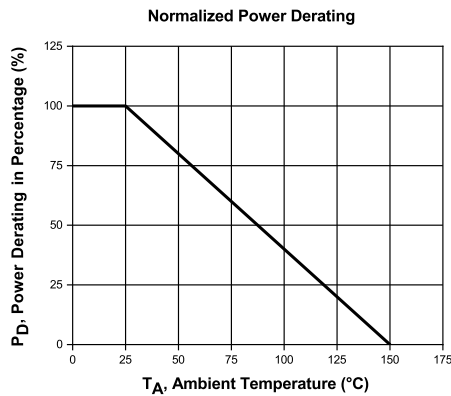
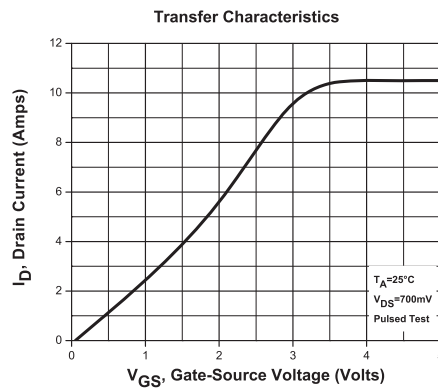
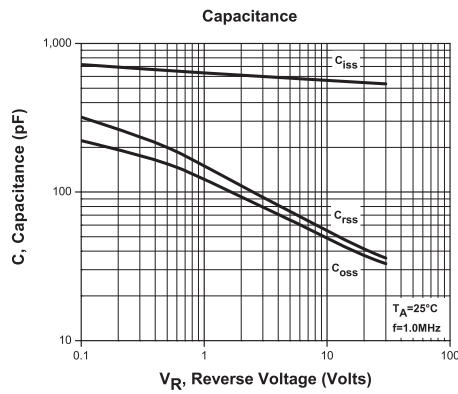
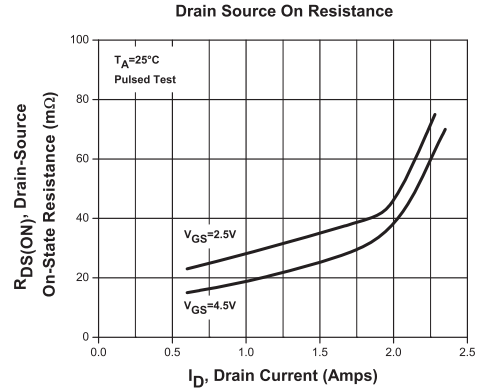
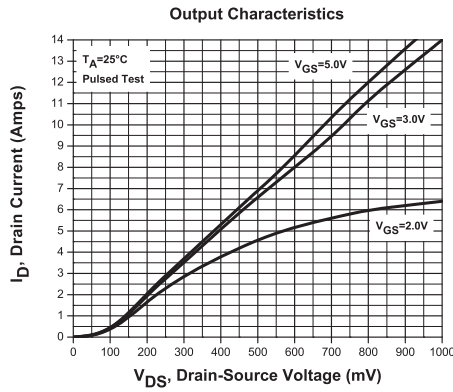
	SYMBOL		UNITS
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	12	V
Continuous Drain Current (Steady State)	$I_D$	3.6	A
Maximum Pulsed Drain Current, $t_p=10\mu\text{s}$	$I_{DM}$	14.4	A
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

#### ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$I_{GSSF}, I_{GSSR}$	$V_{GS}=12\text{V}, V_{DS}=0$			10	$\mu\text{A}$
$I_{DSS}$	$V_{DS}=20\text{V}, V_{GS}=0$			1.0	$\mu\text{A}$
$BV_{DSS}$	$V_{GS}=0, I_D=250\mu\text{A}$	30			V
$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	0.6		1.2	V
$r_{DS(ON)}$	$V_{GS}=4.5\text{V}, I_D=1.8\text{A}$			0.04	$\Omega$
$r_{DS(ON)}$	$V_{GS}=2.5\text{V}, I_D=1.8\text{A}$			0.078	$\Omega$
$g_{FS}$	$V_{DS}=5.0\text{V}, I_D=3.6\text{A}$		11.8		S
$C_{rss}$	$V_{DS}=10\text{V}, V_{GS}=0, f=1.0\text{MHz}$		55		pF
$C_{iss}$	$V_{DS}=10\text{V}, V_{GS}=0, f=1.0\text{MHz}$		590		pF
$C_{oss}$	$V_{DS}=10\text{V}, V_{GS}=0, f=1.0\text{MHz}$		50		pF
$Q_{g(tot)}$	$V_{DD}=10\text{V}, V_{GS}=4.5\text{V}, I_D=3.6\text{A}$			13	nC
$Q_{gs}$	$V_{DD}=10\text{V}, V_{GS}=4.5\text{V}, I_D=3.6\text{A}$			1.4	nC
$Q_{gd}$	$V_{DD}=10\text{V}, V_{GS}=4.5\text{V}, I_D=3.6\text{A}$			2.7	nC
$t_{on}$	$V_{DD}=10\text{V}, V_{GS}=4.0\text{V}, I_D=3.6\text{A}, R_G=10\Omega$		15		ns
$t_{off}$	$V_{DD}=10\text{V}, V_{GS}=4.0\text{V}, I_D=3.6\text{A}, R_G=10\Omega$		29		ns

# CP398X-CPDM303NH

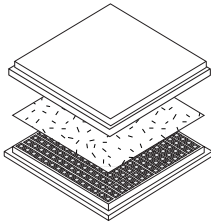
## Typical Electrical Characteristics





## BARE DIE PACKING OPTIONS

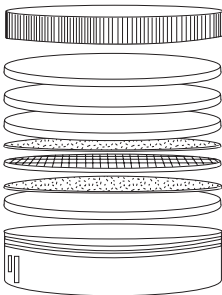
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### BARE DIE IN TRAY (WAFFLE) PACK

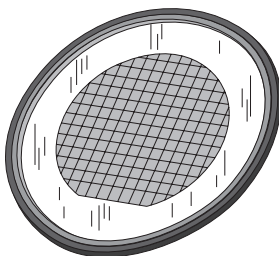
**CT:** Singulated die in tray (waffle) pack.  
(example: **CP211-PART NUMBER-CT**)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: **CP211-PART NUMBER-CM**)



### UNSAWN WAFER

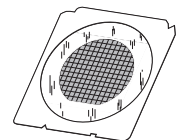
**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: **CP211-PART NUMBER-WN**)



### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: **CP211-PART NUMBER-WR**)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)



## OUTSTANDING SUPPORT AND SUPERIOR SERVICES

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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
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- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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